



LTM8046 51LD BGA-PBF 15mm X 9mm X 4.92mm (TABLE OF MATERIAL DECLARATION)

This Package is RoHS compliant per EU RoHS Directive 2003/95/EC.
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+)
polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1344	Bismaleimide/Triazine/Resin/Filler Substance(Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2 non-disclosure	0.02585	19.23
				Continuous Filament Fiber Glass	65997-17-3	0.02292	17.06
				Copper Metal	7440-50-8	0.06734	50.12
				Zinc	7440-66-6	0.00002	0.02
				Chromium(III) Oxide	1308-38-9	0.00001	0.01
				Epoxy Resin	non-disclosure	0.00002	0.01
				Barium Compounds	7727-43-7	0.00535	3.99
				Silica amorphous	7631-86-9	0.00009	0.06
				Calcium Caobonate	471-34-1	0.00000	0.00
				Amine compounds	non-disclosure	0.00008	0.06
				Leveling agent and others	non-disclosure	0.00024	0.18
				Acrylic Resin	non-disclosure	0.01021	7.60
				Copper Compounds	147-14-8	0.00005	0.04
				Talc;not containing fibers like asbestos	14807-96-6	0.00062	0.46
				Aromatic Carbonyl compounds	non-disclosure	0.00058	0.43
				Cyanoguanidine	461-58-5	0.00002	0.01
				Nickel	7440-02-0	0.00079	0.59
				Gold metal or alloy	7440-57-5	0.00017	0.13
				Ecotoxic substances	7440-38-2 7440-28-0	0.00015	0.11
				2	Solder Paste	Alloy	0.0041
				Antimony (Sb)	7440-36-0	0.00021	5.00
3	Components	Passive/Active	0.4435	Iron Powder (Fe)	7439-89-6	0.00000	0.00
				Copper (Cu)	7440-50-8	0.14191	32.00
				Nickel (Ni)	7440-02-0	0.03548	8.00
				Tin (Sn)	7440-31-5	0.01064	2.40
				Ceramic (Ba) Compounds	12047-27-7	0.25544	57.60
4	Active lcs	Silicon	0.0020	Silicon (Si)	7440-21-3	0.00204	100.00
5	Wire	Gold	0.4630	Gold (Au)	7440-57-5	0.46293	99.99
6	Solder Ball	Alloy	0.0885	Tin (Sn)	7440-31-5	0.08540	96.50
				Silver (Ag)	7440-22-4	0.00266	3.00
				Copper (Cu)	7440-50-8	0.00044	0.50
7	Encapsulation	Epoxy Resin	0.4145	Fused Silica	60676-86-0	0.31999	77.20
				Epoxy Resin	non-disclosure	0.03689	8.90
				Phenol Resin	non-disclosure	0.03689	8.90
				Crytalline Silica	14808-60-7	0.01244	3.00
				Carbon Black	1333-86-4	0.00207	0.50
				Metal Hydroxide	non-disclosure	0.00622	1.50
Total Package Weight			1.5500				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts